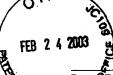
Docket No.: YOR920000578US1 (PATENT)



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Application No.: 09/760,884

Filed: January 17, 2001

For: TUNGSTEN ENCAPSULATED COPPER

INTERCONNECTIONS USING

**ELECTROPLATING** 

Group Art Unit: 1741

Examiner: Smith Hicks

# 3/A 1w.m.

3/5/03

## <u>AMENDMENT</u>

Commissioner of Patents and Trademarks Washington, DC 20231

Dear Sir:

This is in response to the Office Action dated November 22, 2002 (Paper No. 2).

RECEIVED FEB 28 2004 TC 1700 MAIL ROOM

02/26/2003 CNGUYEN 00000119 500510 09760884

01 FC:1202

54.00 CH